



# Product Change Notification

**Change Notification #:** 118767-00  
**Change Title:** Intel® Server Chassis R1304WFXXX  
PCN 118767-00, Product Design,  
Updating Tool-less carrier, adding a gasket on  
the riser bracket and including ODD support  
**Date of Publication:** December 13, 2021

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

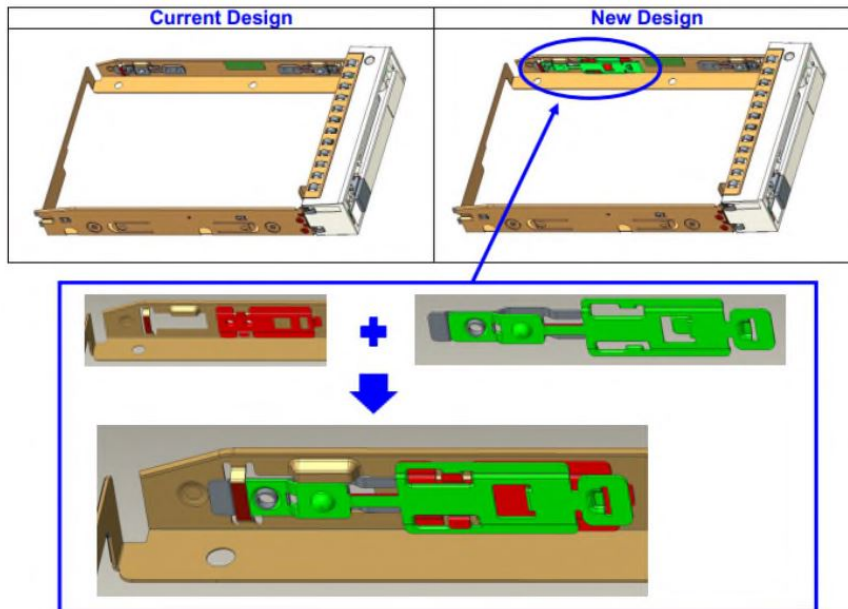
<b>Date Customer Must be Ready to Receive Post-Conversion Material*</b>	December 25, 2021
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

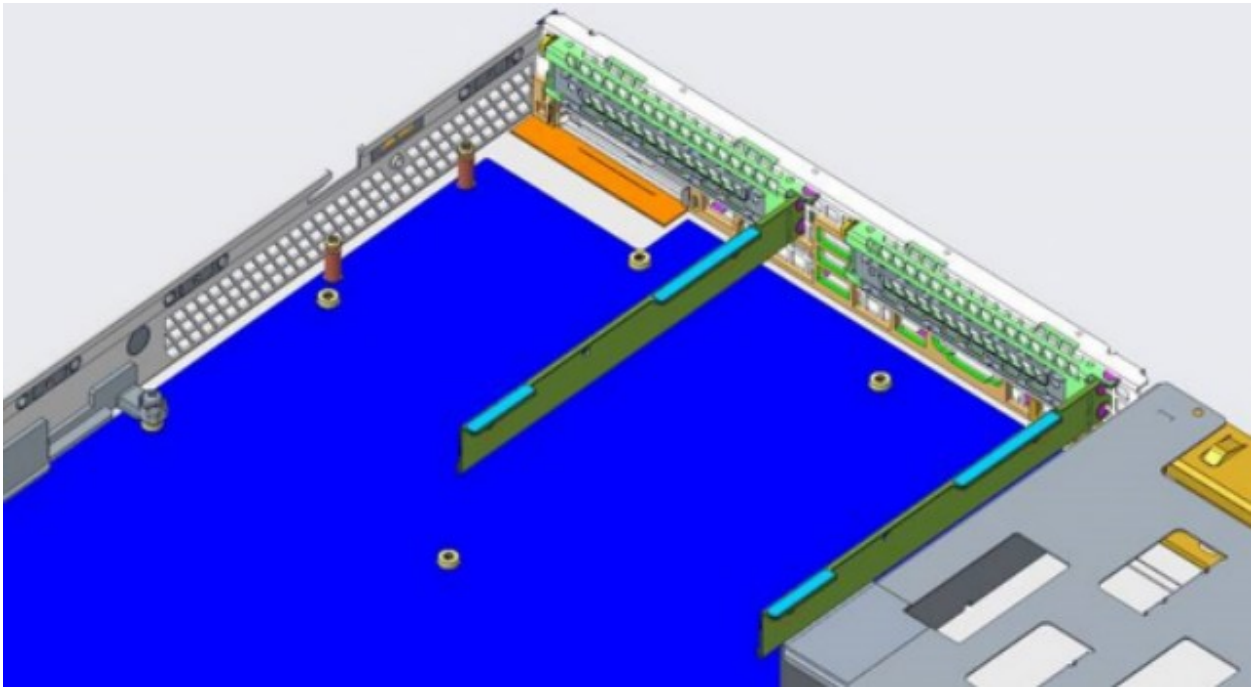
Intel is implementing the following changes to the items in table products affected below.

- For the 3.5" tool-less drive carrier when used for 2.5" drive support, from a non-removable to a new removable rear spring (see image in green) and new spring holder (see image in red) attached to the tool-less drive carrier.

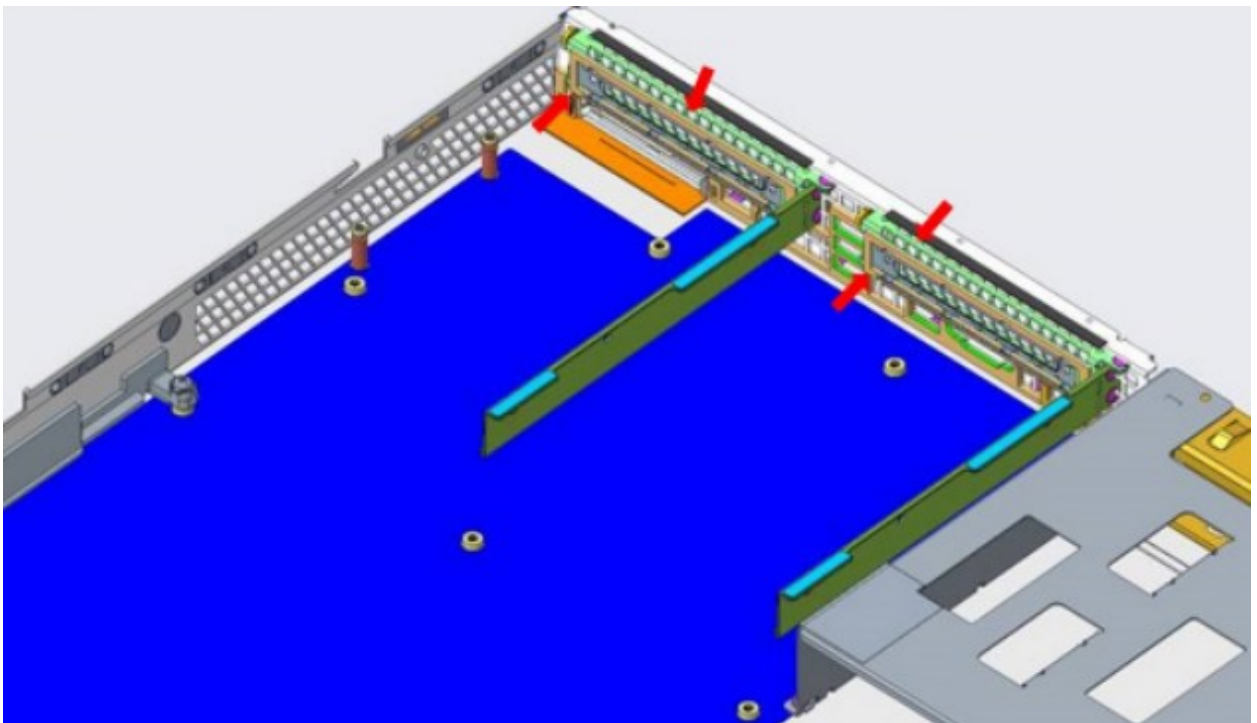


- Removing the new rear spring of 3.5" tool-less carrier when installing 2.5" SSD drive, installing the rear spring to support 3.5" HDD.
- Adding a gasket on the riser bracket to improve the flow of electricity.

Gasket Before



Gasket After



- Including new power cable and bracket for Optical drive support in accessory kit.

### **Customer Impact of Change and Recommended Action:**

Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

### **Products Affected/Intel Ordering Codes:**

<b>Marketing Name</b>	<b>Product Code</b>	<b>MM#</b>	<b>Pre Change TA</b>	<b>Post Change TA</b>
Intel® Server Chassis R1304WFXXX, Single	R1304WFXXX	99AWZA	H81036-006	H81036-007

### **PCN Revision History:**

**Date of Revision:**

December 13, 2021

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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